

AMENDMENTS TO THE CLAIMS

This listing of the claims replaces any and all prior versions and listings of claims in the application:

1.-22. (cancelled)

23. (previously presented) An article having nanoscale patterning, comprising:

a first substrate;

wherein first substrate comprises a first array;

a second substrate;

wherein the second substrate comprises a second array; and

wherein the first array is positioned to face the second array at a distance of less than about 1 micron;

a thin film on the first array;

wherein the thin film covers the first array; and

a plurality of self assembled pillars connecting the first array and the second array at a plurality of junctures of the first array and the second array;

wherein a material of composition of the thin film and a material of composition of the plurality of self assembled pillars are substantially equivalent.

24. (previously presented) The article of claim 23 comprising an electronic device.

25. (previously presented) The article of claim 24, wherein the first and the second substrate comprise a silicon wafer.

26. (previously presented) The article of claim 24, wherein the first array comprises a word-line array.

27. (previously presented) The article of claim 24, wherein the second array comprises a bit-line array.

28. (previously presented) The article of claim 24, wherein the material of composition of the thin film and the plurality of materials comprise a metal.

29. (previously presented) The article of claim 23, wherein the material of composition of the thin film and the pillars is selected from the group consisting of a polymer, a semi-conductor, a metal, a biological material, and mixtures thereof.

30. (previously presented) The article of claim 23, wherein the thin film is on the second array instead of the first array.